© C	terial Compositio opyright 2005. IPC, Ba national and Pan-Amer	nnockbu	rn, Illinois. A	ll rights reserved untions.	nder both	This docume level parts, t	ent is a declara he declaration	tion of encom	the substances passes all low	within the er level mate	manufactur erials for wh	er listed it hich the m	tem. Note: nanufacture	if the item is an a er has engineering	ssembly with low responsibility.	
					Form Type Distribute	* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					ous Materia	als and Mfg Information				
upplier Information																
Company name*			Company unique ID				Unique ID Authority					Response Date*				
nsemi											2024-04-24					
Contact Name			Title - Contact				Phone - Contact*					Email - Contact*				
Product-Env-Stewards			Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com					
Authorized Representative*			Title - Representative				Phone - Representative*				Email - Representative*					
Product-Env-Stewards			Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com					
Requester Item	Requester Item Number Mfr Iten		n Number Mfr Item Name				Effective Dat	e Ve	rsion	Manufacturing Site			Weight*	UOM	Unit Type	
	1N4002G		REC AXIAL 1A 100V STD		2024-04-24			CNP		2	250.82	mg	Each			
Ianufacturing Proce	ess Information															
Terminal Plating / Grid Array Material T		Te	erminal Base Alloy J-STD-020 MSI		L Rating	Peak Process Body Temperatu		ire Max Ti	me at Peak	Temperat	ure Num	ber of Reflow Cy	cles			
Matte Tin (Sn) - annealed		CU	CU Alloy NA			0 C		30		secon	ds 3					
omments																
or more information rega	rding material compo	osition p	lease refer to	page 3												

RoHS Material Composition Declar	ation			Declaration Type *	Detailed
Directive 2015/863/EU amending Rol Directive 2011/65/EU	(Pb), Mercury (Hg), Hexav		ninated Biphenyls (PBB), Polybror	dmium and quantity limit of 0.1% by mass (100 ninated Diphenyl Ethers (PBDE), and Bis(2-eth	
cadmium, hexavalentchromium, polyb contains a RoHS restricted substance i encompass all such components.Suppl as of the date that Supplier completes Company acknowledges that Supplier independently verified information pro- certification in this paragraph.If the Co	rominated biphenyls and/or polybror nexcess of an applicable quantity lim ier certifies that it gathered the inforr this form.Supplier acknowledges that may have relied on informationprovi ovided by others, Supplier agrees that ompany and the Supplier enter into a clusivesource of the Supplier's liabili	ninated diphenyl ethers (each a "R it, please indicate below which, if nation it provides in this form usin Company will rely on this certifud ded by others in completing this f , at a minimum, itssuppliers have written agreement with respect to ty and the Company's remedies for	toHS restricted substance") in exce any, RoHS exemption you believe ag appropriate methods to ensure it cation in determining the complian orm, and that Supplier may not hav provided certifications regarding th the identified part,the terms and co or issues that arise regarding inform	ropean Union member states) of the part identifies so of the applicable quantity limit identified about may apply. If the part is an assembly with lows a accuracy and that such information is true and ce of its products with European Union member re independently verified such information. How heir contributions to the part, and those certifica motions of that agreement, including any warra nation the Supplier provides in this form. In the	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the inty rights and/or remedies provided as part of
<b>RoHS Declaration *</b> 4	- Item(s) does not contain RoHS restr	icted substances per the definition	above except for selected exempti	ons Supplier Acceptance	* Accepted
Exemption: 7a: Lead in high meltin Exemption: 7c-I Electrical and elect	g temperature type solders (i.e. lead ronic components containing lead i	l based solder alloys containing n a glass or ceramic other than	85% by weight or more lead). dielectric ceramic in capacitors, o	e.g. piezoelectronic devices, or in a glass or ce	eramic matrix compound.
Exemption List Version	EL-2011/534/EU				
Declaration Signature					
Instructions: Complete all of the rec Requester) and click on Submit For			Supplier Acceptance drop-down	. This will display the signature area. Digital	ly sign the declaration (if required by the
Supplier Digital Signature	Rastislav Drska	Le			

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.18	mg	Supplier	Silicon (Si)	7440-21-3		0.1682	mg
			В	Nickel (Ni)	7440-02-0		0.0021	mg
			Supplier	Lead Bisilicate	65997-18-4	7c	0.0097	mg
Die Attach Solder	7.98	mg	Supplier	Silver (Ag)	7440-22-4		0.1995	mg
			А	Lead (Pb)	7439-92-1	7a	7.3815	mg
			Supplier	Tin (Sn)	7440-31-5		0.399	mg
Lead Frame	125.08	mg	Supplier	Copper (Cu)	7440-50-8		125.08	mg
Mold Compound-Black	116.8	mg		Metal Hydroxide	proprietary data		5.84	mg
			Supplier	Carbon Black (C)	1333-86-4		1.168	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		87.6	mg
			Supplier	Ortho-Cresol Novolac Resin	29690-82-2		11.68	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		10.512	mg
Plating	0.78	mg	Supplier	Tin (Sn)	7440-31-5		0.78	mg